

Infineon X-GOLD™ 213 – eWLB Package

Reverse Costing Analysis

by System Plus Consulting

The First Reverse Analysis Report of a Fan-out Wafer Level Package!

System Plus Consulting is proud to publish the reverse costing report of the enhanced Wafer Level BGA (eWLB) package used in the X-GOLD™ 213 circuit from Infineon.

eWLB is a Ball Grid Array package based on the emerging Fan-Out Wafer Level Package (FO-WLP) concept. All the packaging operations are done at the wafer level, and a fan-out area is provided, which extends the package size beyond the IC surface area to allow for higher ball counts. The ball pitch is 0.5mm and only one redistribution layer is used for this 217 balls 8x8 mm package.

The eWLB is manufactured on 200 mm wafers by Infineon who licensed the technology to ASE and STATChipPAC.

This report provides for a complete teardown of the X-GOLD 213™ eWLB package including:

- Detailed photos
- Material analysis
- Manufacturing Process Flow
- In-depth economical analysis
- Manufacturing cost breakdown
- Selling price estimation

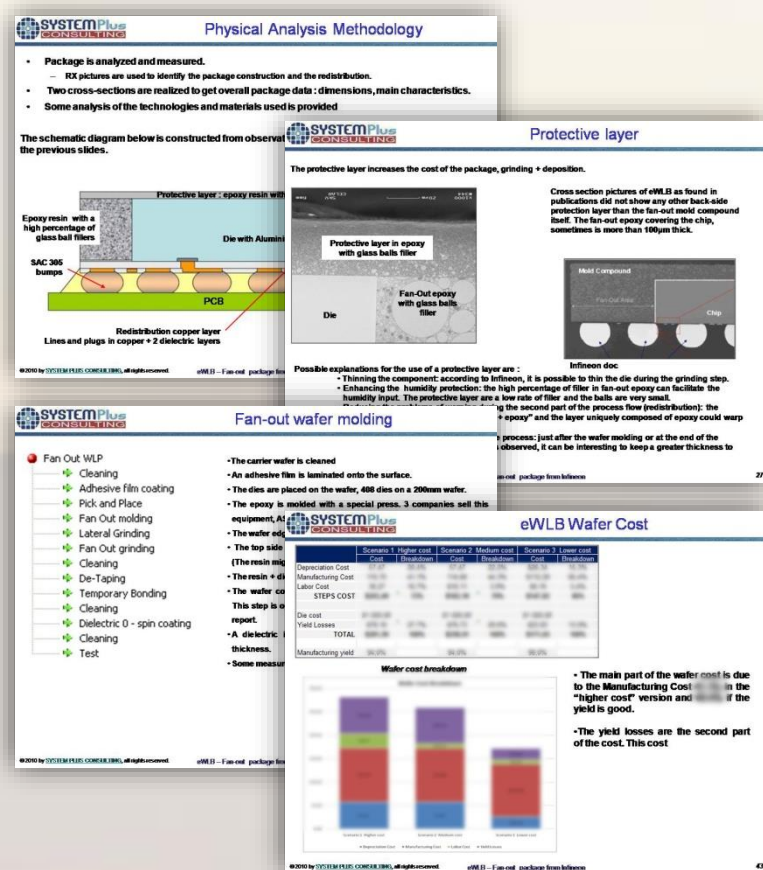


TABLE OF CONTENTS

Glossary	p3	Manufacturing Process Flow	p31
Overview / Introduction	p4	• The Process Flow Main Steps	
• Executive Summary		• eWLB Process Flow	
• Reverse Costing Methodology		• Fan-out Wafer Molding	
Fan-out package Principle	p7	• Redistribution	
• Fan-in & Fan-out WLP		• Bumping and Dicing	
• Benefits of eWLB		Cost Analysis	p39
• eWLB – Reconstitution Flow		• Synthesis of the Cost Analysis	
Physical Analysis	p12	• Assumptions	
• Physical Analysis Methodology		• Packaging Yields	
• Synthesis		• eWLB Wafer Cost	
• Mobile Phone & PCB		• Wafer Cost per Equipment Type	
• Underfill		• Wafer Cost per Consumable Type	
• Die in the package		• eWLB Package Cost	
• Pads and the redistribution layer		Estimated Manufacturer Price Analysis	p47
• The die Shift issue		• Price definitions	
• Fan-out		• Manufacturers financial ratios	
• Protective layer		• Estimated manufacturer Price	
• Redistribution layer		Conclusion	p51
• Bumping process			

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